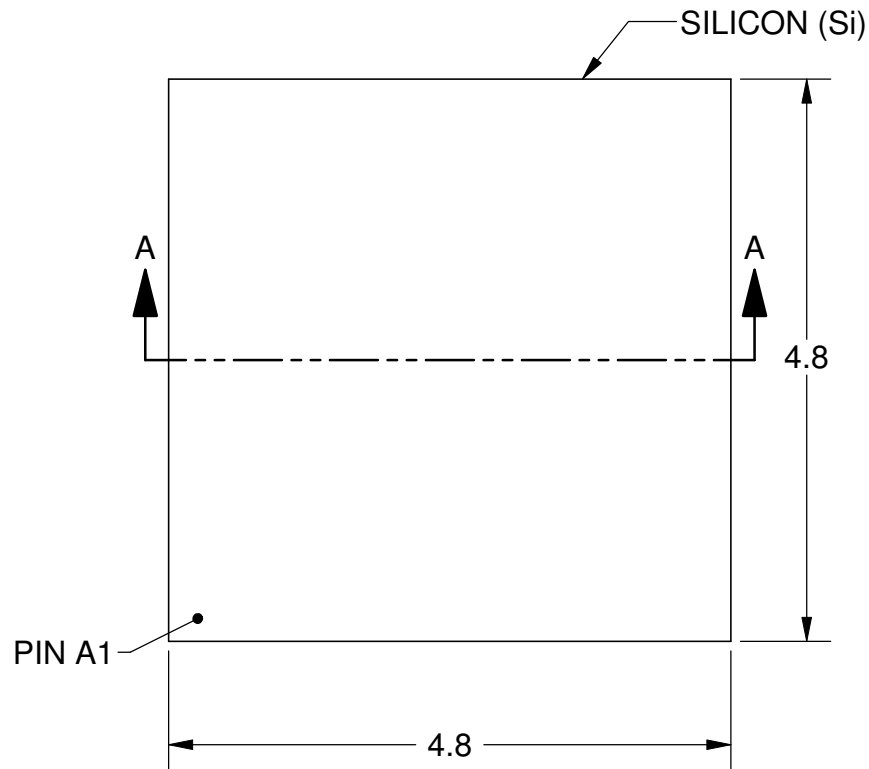
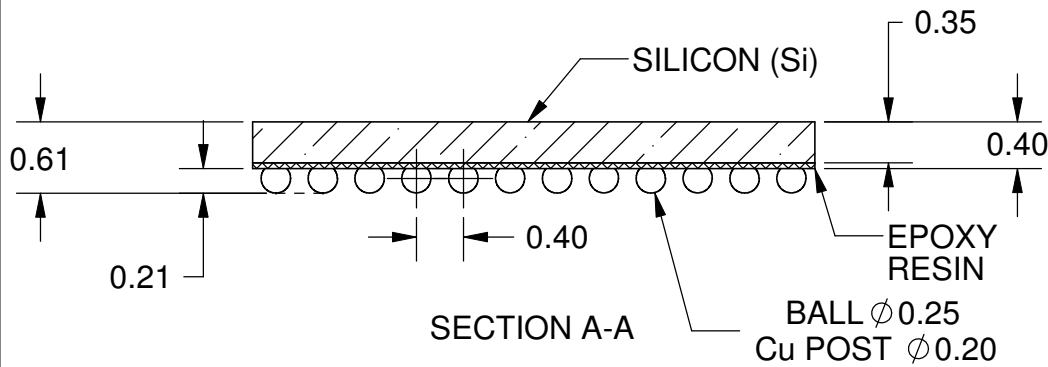
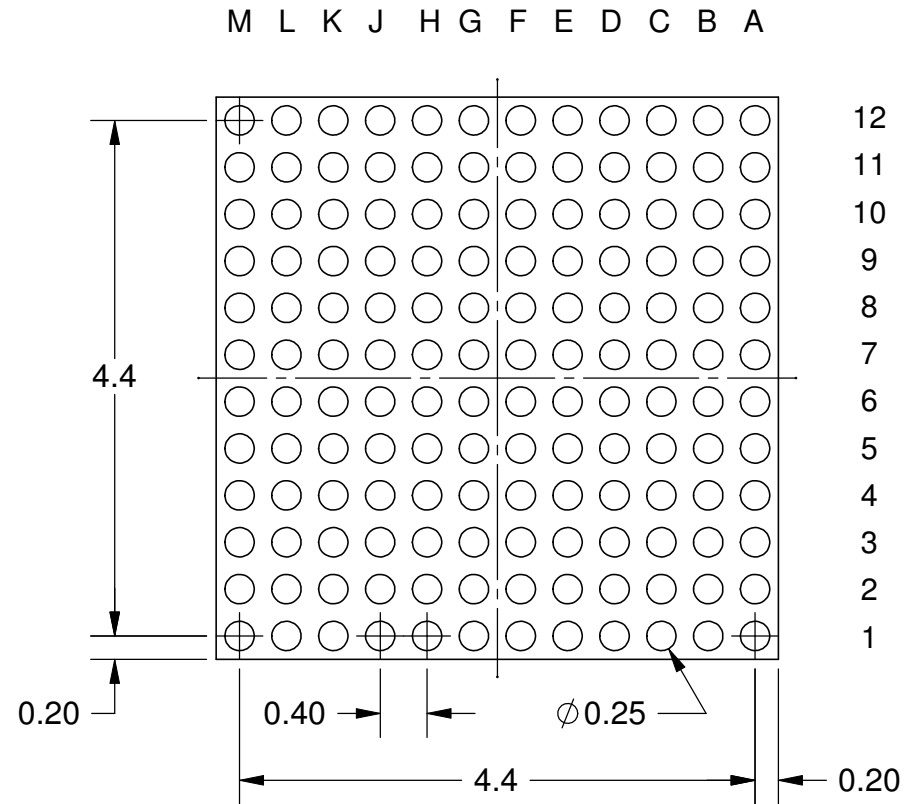


TOP VIEW



BALL VIEW



Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY:
STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
SPECIAL: LF35 (Sn98.3/Ag1.2/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: 0.20mm.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN PATTERN (SEE PAGE 2).

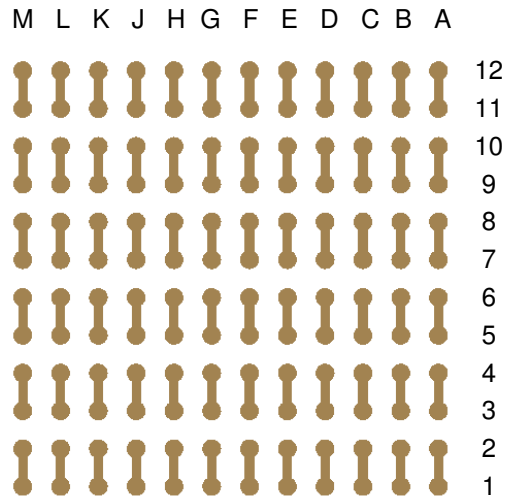
PART NUMBER TABLE

PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP144T.4C-DC127D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
WLP144T.4C1-DC127D	Sn98.3/Ag1.2/Cu0.5	YES	YES	YES

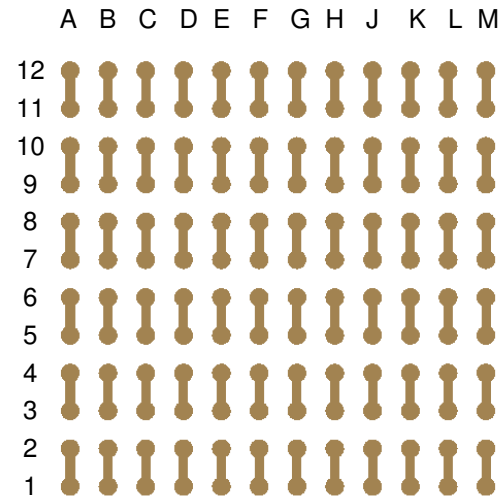
TOLERANCE UNLESS NOTED		APPROVALS		DATE	TopLine [®]			
X.X	+/- 0.3	DRAWN J. Hines		12/30/2010				
X.XX	+/- 0.03	ENG			TITLE WLP144T.4C-DC127D			
X.XXX	+/- 0.003	MFG			144-BALL P=0.4mm (TEG0408)			
ANGLES +/- 0.5°		THIRD ANGLE PROJECTION			SCALE	SIZE	DRAWING NO.	REV
ALL DIMENSIONS IN		<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS			15.5:1	A	541272	A
					DO NOT SCALE DRAWING		SHEET 1 OF 2	

DAISY CHAIN PATTERN

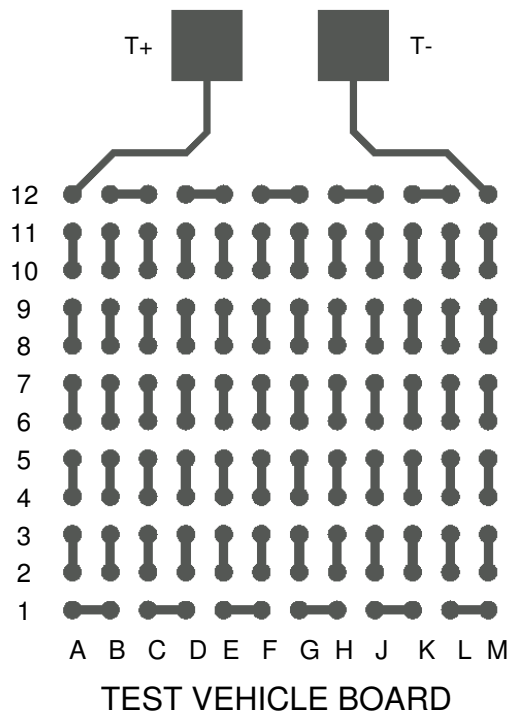
BALL VIEW



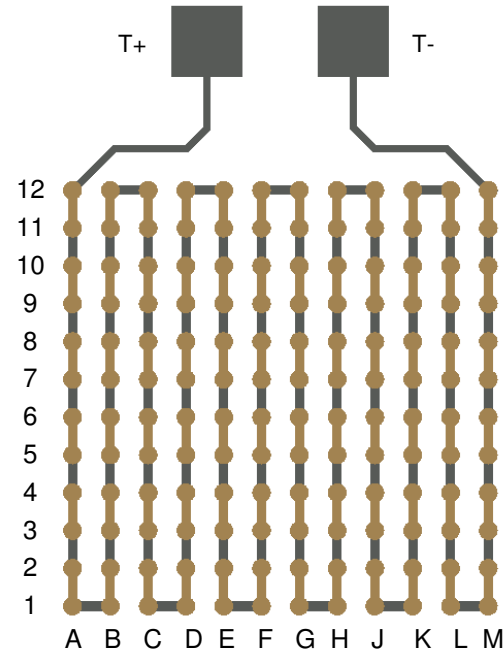
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.20mm (7.8mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).

TopLine ®			
TITLE WLP144T.4C-DC127D 144-BALL P=0.4mm (TEG0408)			
SCALE	SIZE	DRAWING NO.	REV
12.5:1	A	541272	A
DO NOT SCALE DRAWING			SHEET 2 OF 2